

**VERSION WITH MARKINGS TO SHOW CHANGES MADE
IN THE SPECIFICATION:**

Paragraph beginning at line 5 of page 1 has been amended as follows:

5 The invention relates to a packaging structure of image sensors and method for packaging the same, and in particular, to a packaging structure in which a substrate for carrying an image sensing chip is formed using plastic materials and the substrate includes metallic pins, thereby lowering the manufacturing costs.

Paragraph beginning at line 14 of page 4 has been amended as follows:

10 The substrate 10 includes a plurality of straight metal sheets 16 directly penetrating through the substrate, glue 18 for sealing the metal sheets 16, a first surface 20, and a second surface 22. Referring to FIG. 2, the method for manufacturing the substrate 10 includes the following steps. First, adhere the plurality of metal sheets 16 onto a tape 24. Next, place the tape 24 on a mold
15 (not shown). Then, pour the glue into the mold, the glue can be a plastic material such as epoxy mold compound, BT, FR4, FR5, PPE, or the like. Thereafter, tear the tape 24 to complete the manufacturing processes of the substrate 10, as shown in FIG. 3. At this time, the metal sheets 16 are exposed to the outside via both of the first surface 20 and the second surface 22 of the
20 substrate 10, respectively, in order to form first contacts 26 and second contacts 28 on the substrate 10. Alternatively, a projecting edge 30 is formed around the first surface 20 of the substrate 10 in order to form a concavity 32 for containing the image sensing chip 12. The projecting edge 30 can be integrally formed with the substrate 10. Optionally, the projecting edge 30 also can be made of plastic
25 materials, and then, the projecting edge 30 is adhered onto the substrate 10. Thus, the transparent layer 14 can be placed on the projecting edge 30 in order to seal the image sensing chip 12 which can receive optical signals.

IN THE CLAIMS:

Claim 1 has been amended as follows:

- 30 1. (Amended) A packaging structure of an image sensor, comprising:
a substrate including a plurality of straight metal sheets directly penetrating

through the substrate, glue for sealing the metal sheets, a first surface having a periphery, and a second surface opposite to the first surface, the metal sheets being exposed to the outside via the first surface and the second surface to form first contacts and second contacts, respectively;

5 a projecting edge ~~being provided~~ on the periphery of the first surface of the substrate to form a concavity above the substrate;

an image sensing chip mounted on the substrate and within the concavity, a plurality of bonding pads being formed on the image sensing chip;

10 a plurality of wirings electrically connecting the bonding pads of the image sensing chip to the first contacts of the first surface of the substrate in order to electrically connect the image sensing chip to the substrate, so that electrical signals from the image sensing chip are capable of being transmitted to the second contacts of the second surface of the substrate; and

15 a transparent layer arranged on the projecting edge on the first surface of the substrate so that the image sensing chip is capable of receiving ~~the~~ optical signals.

Claim 6 has been amended as follows:

6. (Amended) A method for packing an image sensor, comprising the steps

of:

20 preparing a substrate including a plurality of straight metal sheets directly penetrating through the substrate, glue for sealing the metal sheets, a first surface having a periphery, and a second surface opposite to the first surface, the metal sheets being exposed to the outside via the first surface and the second surface to form first contacts and second contacts, respectively;

25 providing a projecting edge ~~being provided~~ on the periphery of the first surface of the substrate to form a concavity above the substrate;

mounting an image sensing chip ~~the substrate~~ having a plurality of bonding pads onto ~~of the first surface of the substrate and within the concavity of the first surface of the substrate~~;

30 connecting the bonding pads of the image sensing chip to the first contacts of the first surface of the substrate by a ~~the~~ plurality of wirings; and

mounting a transparent layer on the projecting edge located on the first surface of the substrate in order to cover the image sensing chip.